SZCJ

Shenzhen Changji Semiconductor Co., LTD.

SMAG Plastic-Encapsulate Diodes

GS1AA THRU GS1MA General Purpose Rectifier Diodes

Features

- $I_{F(AV)}$ 1A
- V_{RRM} 50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

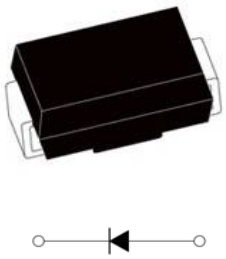
Applications

- Rectifier

Marking

- G1X
  X：From A To M

SMAG



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	GS1						
				AA	BA	DA	GA	JA	KA	MA
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V_{DC}	V		50	100	200	400	600	800	1000
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, TL=100℃	1						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave,1 cycle, Ta=25℃	30						
Junction Temperature	T_J	℃		-55~+150						
Storage Temperature	T_{STG}	℃		-55 ~ +150						

Electrical Characteristics (T_a=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		Max
Peak Forward Voltage	V_{FM}	V	I_{FM}=1.0A		1.0
Peak Reverse Current	I_{RRM1}	μA	$V_{RM}=V_{RRM}$	T_J=25℃	5
	I_{RRM2}			T_J=125℃	50
Reverse Recovery Time (Typical)	Trr	us	I_F=0.5A I_R=1A I_{RR}=0.25A		1.8
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C.		7
Thermal Resistance (Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		55
	$R_{\theta J-L}$		Between junction and lead		25

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

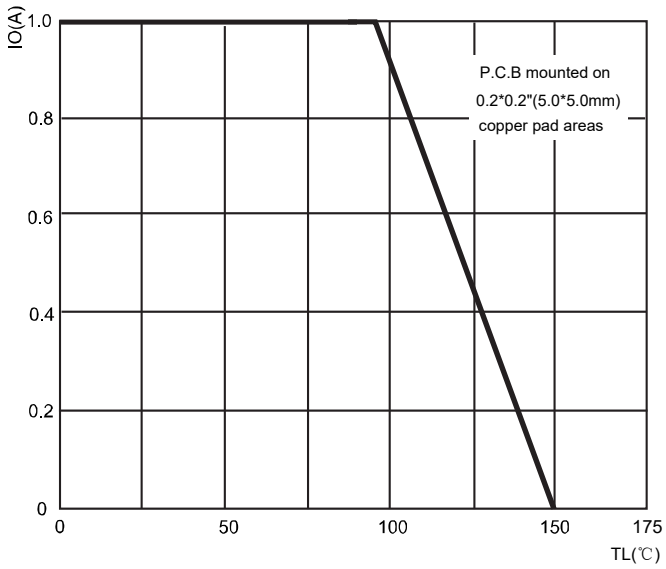


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

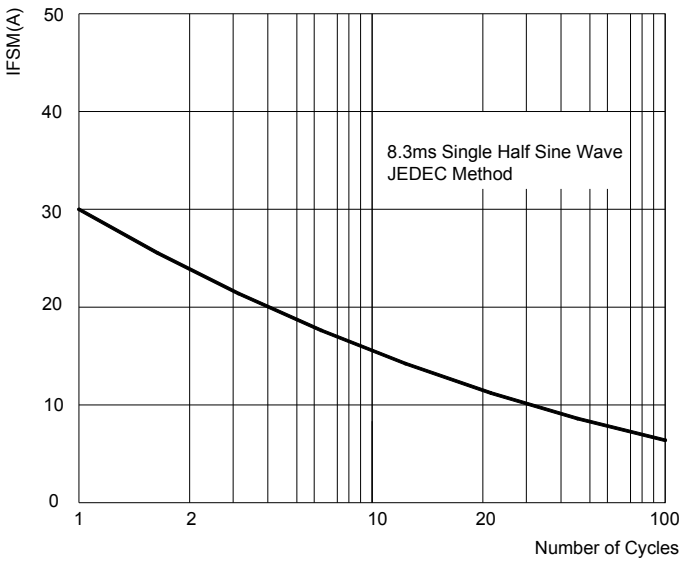


FIG.3: TYPICAL FORWARD CHARACTERISTICS

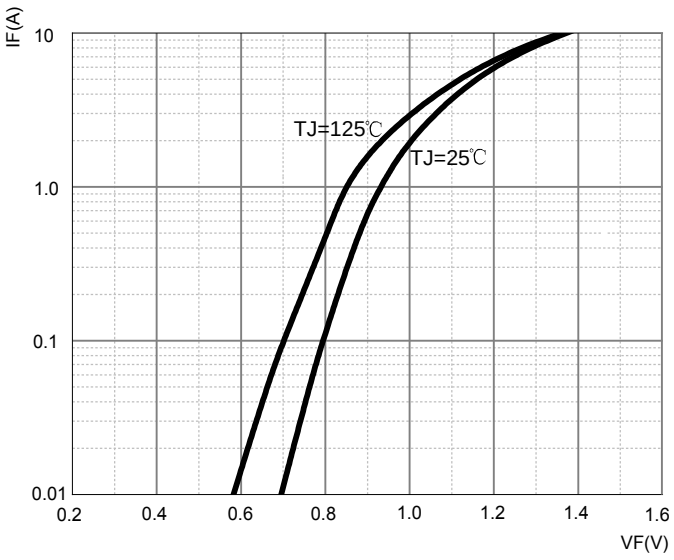
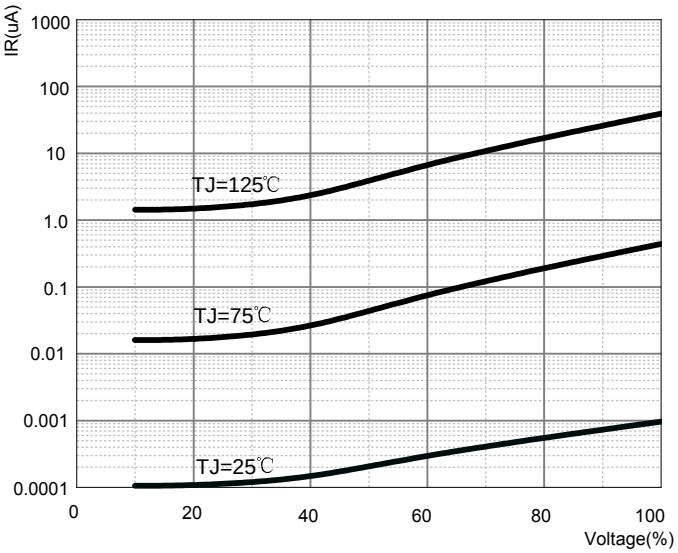
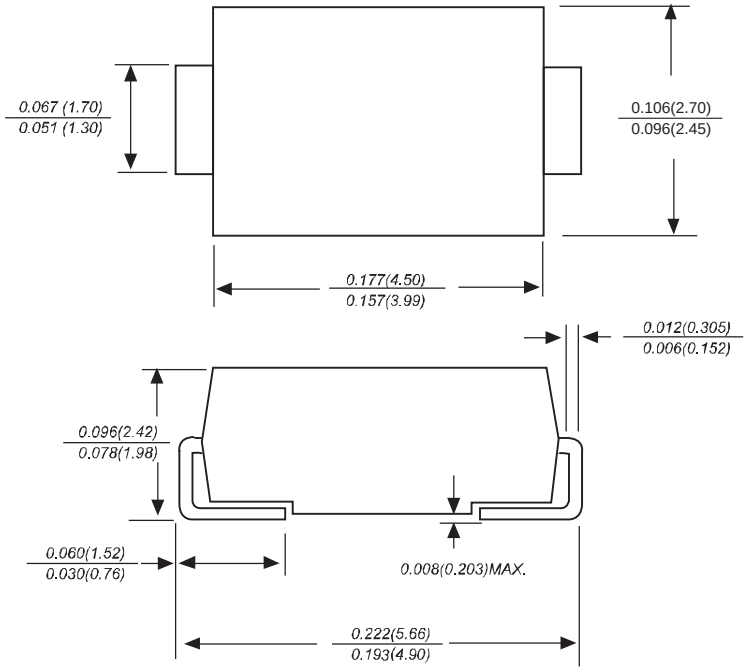


FIG.4:TYPICAL REVERSE CHARACTERISTICS

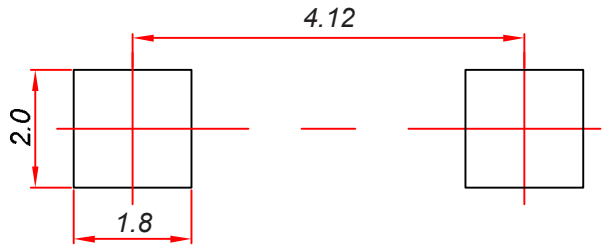


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

SZCJ reserves the right to make modifications,enha nts,improvements,corrections or other es without further notice to any product herein.SZCJ does not assume any liability arising out of the application or use of any product described .

Reel Taping Specifications For Surface Mount Devices- SMAG

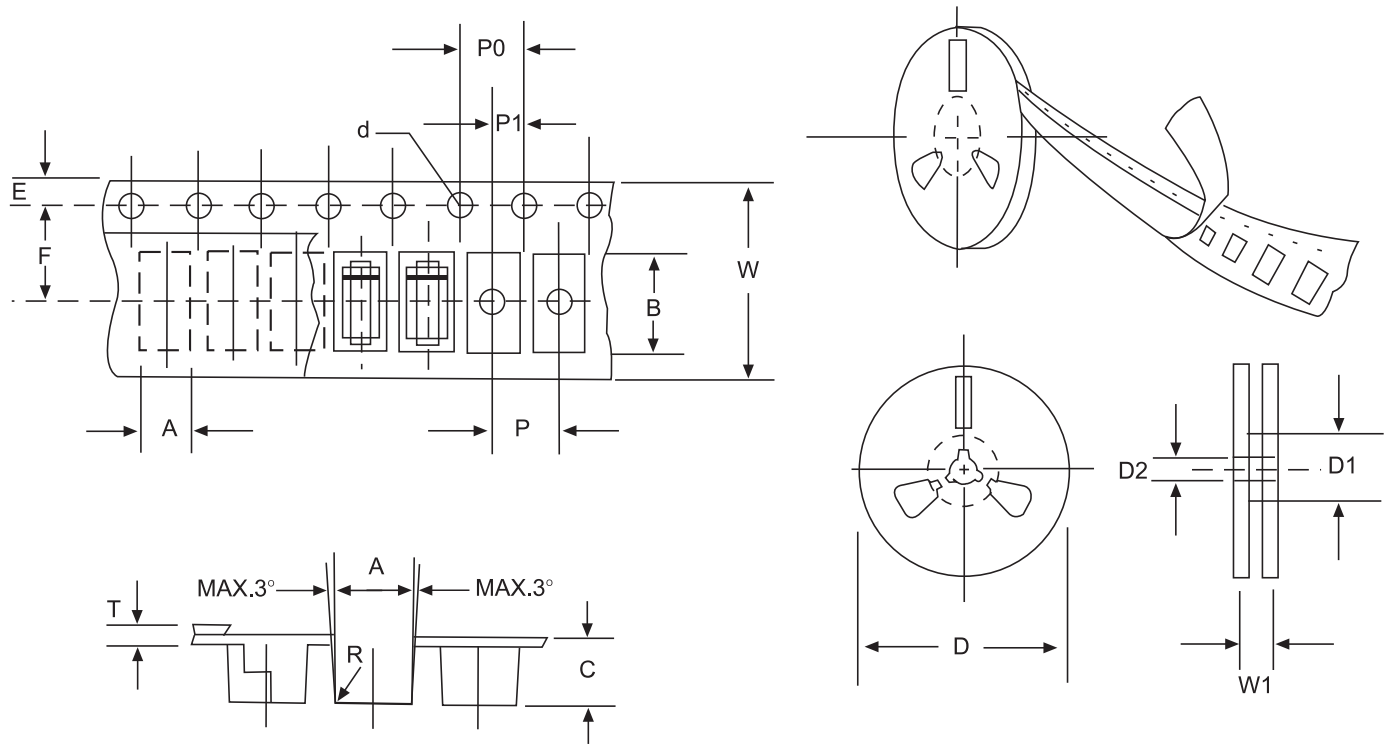


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packed in accordance with EIA standard RS-481-A and specification given above.